

Title (en)

MANAGING THERMAL BUDGET IN ANNEALING OF SUBSTRATES

Title (de)

VERWALTUNG DES WÄRMEBUDGETS BEIM GLÜHEN VON SUBSTRATEN

Title (fr)

GESTION DU BUDGET THERMIQUE DANS LE RECUIT DE SUBSTRATS

Publication

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Application

EP 09814993 A 20090903

Priority

- US 2009055838 W 20090903
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- US 21221408 A 20080917

Abstract (en)

[origin: WO2010033389A1] A method and apparatus are provided for treating a substrate. The substrate is positioned on a support in a thermal treatment chamber. Electromagnetic radiation is directed toward the substrate to anneal a portion of the substrate. Other electromagnetic radiation is directed toward the substrate to preheat a portion of the substrate. The preheating reduces thermal stresses at the boundary between the preheat region and the anneal region. Any number of anneal and preheat regions are contemplated, with varying shapes and temperature profiles, as needed for specific embodiments. Any convenient source of electromagnetic radiation may be used, such as lasers, heat lamps, white light lamps, or flash lamps.

IPC 8 full level

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CPC (source: EP KR)

H01L 21/324 (2013.01 - EP KR); **H01L 21/67115** (2013.01 - EP)

Citation (search report)

- [X] EP 0091806 A2 19831019 - FUJITSU LTD [JP]
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- See references of WO 2010033389A1

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DOCDB simple family (publication)

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